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Resin-moulded semiconductor hybrid module and manufacturing method thereof

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☐ JP11233712, ☐ US6291880

Cited

Documents: [EP0774782](#); [US5699609](#); [US5077595](#); [JP8298299](#)**Abstract**

A semiconductor device includes a main circuit part having a semiconductor device formed on an electrode plate (13) of a lead frame and a control circuit part having protective functions, which is integrally molded by a resin mold part (30) into an integral mold structure. 

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